Product Change Notification: DSNO-22PBDH859

Date:

20-Oct-2026

Product Category:

Memory

Notification Subject:

CCB 8073 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for SST25VF016B-50-4I-S2AF-GYR-T, SST25VF016B-50-4I-S2AF-GYR, SST25VF016B-50-4C-S2AF-T, SST25VF016B-50-4I-S2AF-T, SST25VF016B-50-4I-S2AF and SST25VF016B-50-4C-S2AF catalog part numbers (CPN) available in 8L SOIJ (.208in) package.

Affected CPNs:

DSNO-22PBDH859_Affected_CPN_10202026.pdf
DSNO-22PBDH859_Affected_CPN_10202026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for SST25VF016B-50-4I-S2AF-GYR-T, SST25VF016B-50-4I-S2AF-GYR, SST25VF016B-50-4C-S2AF-T, SST25VF016B-50-4I-S2AF-T, SST25VF016B-50-4I-S2AF and SST25VF016B-50-4C-S2AF catalog part numbers (CPN) available in 8L SOIJ (.208in) package.

Pre and Post Summary Changes:

	Pre Change	**Post Change**	**Change (Yes/No)**
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No
Wire Material	Au	CuPdAu	Yes

	Pre Change	Post Change	Change (Yes/No)
Die Attach Material	8006NS (PFAS-free)	8006NS (PFAS-free)	No
Molding Compound Material	G600V	G600V	No
Lead-Frame Material	A194	A194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material.

Change Implementation Status: In Progress

Estimated First Ship Date: 10 November 2026 (date code: 2646)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	March 2026					>	October 2026					November 2026				
Work Week	10	11	12	13	14		40	41	42	43	44	45	46	47	48	49
Initial PCN Issue Date		x														
Qual Report Availability										x						
Final PCN Issue Date										x						
Estimated Implementation Date													x			

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: March 13, 2026: Issued initial notification.
October 20, 2026: Issued final notification. Updated the reason for change to reflect palladium coated copper with gold flash (CuPdAu). Attached the qualification report. Provided estimated first ship date to be on November 11, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN DSNO-22PBDH859 Qual Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN):

SST25VF016B-50-4I-S2AF-GYR-T

SST25VF016B-50-4I-S2AF-GYR

SST25VF016B-50-4C-S2AF-T

SST25VF016B-50-4I-S2AF-T

SST25VF016B-50-4I-S2AF

SST25VF016B-50-4C-S2AF



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: DSNO-22PBDH859

Date

October 8, 2026

Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for SST25VF016B-50-4I-S2AF-GYR-T, SST25VF016B-50-4I-S2AF-GYR, SST25VF016B-50-4C-S2AF-T, SST25VF016B-50-4I-S2AF-T, SST25VF016B-50-4I-S2AF and SST25VF016B-50-4C-S2AF catalog part numbers (CPN) available in 8L SOIJ (.208in) package.

PACKAGE QUALIFICATION REPORT

Purpose:	Qualification of palladium coated copper with gold flash (CuPdAu) as a new wire material for SST25VF016B-50-4I-S2AF-GYR-T, SST25VF016B-50-4I-S2AF-GYR, SST25VF016B-50-4C-S2AF-T, SST25VF016B-50-4I-S2AF-T, SST25VF016B-50-4I-S2AF and SST25VF016B-50-4C-S2AF catalog part numbers (CPN) available in 8L SOIJ (.208in) package.
QUAL ID:	R2600364
QUAL ID Rev.:	A
MP CODE:	T0001T4BXD50
Part No.:	SST25VF016B-50-4I-S2AF-T
Bonding No.:	BD-004168-01
CCB No.:	8073

Lead Frame

Paddle Size:	140x160 mils.
Material:	A194
DAP Surface Prep:	NiPdAu
Process:	Stamped
Lead Lock:	No
Part Number:	10100837
Lead Plating:	NiPdAu
Treatment:	Roughening LF

Bond Wire

Wire:	CuPdAu wire

Die Attach Material

Epoxy:	8006NS
Conductive:	No

Mold Compound

Mold Compound:	G600V

Package

Type:	8L SOIJ
Package Size:	0.208"

Manufacturing Information

Assembly Lot No.
MTAI264800266.000
MTAI264800267.000
MTAI264800381.000

Result: **Pass**

Conclusion:
Qualification of T0001 mask / SST25VF016B-50-4I-S2AF-T product / CuPdAu wire in 8L SOIJ 0.208" package at MTAI site is qualified for MSL3 at 260ºC as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Moisture Soak Precondition Prior to Stresses	**MSL3:** 150°C 24 hours Bake, 192 hours Moisture Soak at 30°C/60%RH, 3x Reflow at 260°C **Electrical Test:** Tester: NEXTEST_PV2, 25°C and 85°C	JESD22-A113 , JEDEC J-STD-020	231(0)	0/231	Pass	
High Temp Storage	175°C / 504 hours **Electrical Test:** Tester: NEXTEST_PV2, 25°C and 85°C	JESD22-A103	45 (0)	0/45	Pass	
Temperature Cycling	-65°C / +150°C Air to Air / 500 Cycles **Electrical Test:** Tester: NEXTEST_PV2, 85°C	JESD22-A104	77(0)	0/77	Pass	
	WBP (Wire Bond Pull) - Lot 1 only		5(0)	0/5	Pass	Lot 1 only, N/A for Lot 2 and Lot 3
Biased HAST	+130°C / 85%RH / 96 hours / Bias Voltage: 3.6V **Electrical Test:** Tester: NEXTEST_PV2, 25°C and 85°C	JESD22-A110	77(0)	0/77	Pass	
Unbiased HAST	+130°C / 85%RH / 96 hours **Electrical Test:** Tester: NEXTEST_PV2, 25°C	JESD22-A118	77(0)	0/77	Pass	
Wire Pull	Bond Strength Data Assembly	Mil. Std. 883-2011	5(0)	0/5	Pass	
Bond Shear	Bond Strength Data Assembly	CDF-AEC-Q1 00-001	5(0)	0/5	Pass	
Bond Line Thickness	0.60-1.50mils	SPI-45528	15(0)	0/15	Pass	
Wire sweep	15%	X-ray	45(0)	0/45	Pass	